



Product/Process Change Notice - PCN 13_0205 Rev. -

Analog Devices, Inc. Three Technology Way Norwood, Massachusetts 02062-9106

This notice is to inform you of a change that will be made to certain ADI products (see Material Report). Any issues with this PCN or requirements to qualify the change (additional data or samples) must be sent to ADI within 30 days of publication date. ADI contact information is listed below.

PCN Title: Assembly and Test Transfer of Select 3x3mm LFCSP Products to Amkor Philippines

Publication Date: 25-Nov-2013

Effectivity Date: 15-Apr-2014 *(the earliest date that a customer could expect to receive changed material)*

Revision Description:

Initial Release

Description Of Change

ADI is transferring to subcontractor Amkor Philippines for the assembly and test manufacturing of select 3x3 LFCSP products. The package outline dimensions, wire diameter and die attach epoxy of each product will be maintained. The mold compound is changing from Sumitomo G770 to Sumitomo G700. See BOM attachment for details.

Reason For Change

ADI is transferring to Amkor Philippines due to the closure of STATS ChipPAC Malaysia at the end of 2014.

ADI's assembly subcontractors manufacture products using Analog Devices specified manufacturing flows, materials, process controls and monitors, ensuring the same level of quality and reliability on products they receive from the new site.

Impact of the change (positive or negative) on fit, form, function & reliability

The Transfer will have no impact on the form, fit, function and reliability of the devices.

Product Identification *(this section will describe how to identify the changed material)*

The parts that will be assembled after the transfer will be identified by assembly lot and the country of origin.

Summary of Supporting Information

Qualification will be performed per AEC-Q100, Stress Test Qualification for Integrated Circuits. See attached Qualification Plan Summary. Test correlation and validation will also be performed. See attached Test Plan.

Supporting Documents

Attachment 1: Type: Qualification Plan Summary

ADI_PCN_13_0205_Rev_-_Automotive Reliability Qualification Plan.pdf

Attachment 2: Type: Test Correlation Plan

ADI_PCN_13_0205_Rev_-_Test Plan.pdf

For questions on this PCN, send email to the regional contacts below or contact your local ADI sales representative

Americas: PCN_Americas@analog.com

Europe: PCN_Europe@analog.com

Japan: PCN_Japan@analog.com

Rest of Asia: PCN_ROA@analog.com

Appendix A - Affected ADI Models

Added Parts On This Revision - Product Family / Model Number (7)

AD8137 / AD8137WYCPZ-R7	AD8137 / AD8137YCPZ-REEL	AD8137 / AD8137YCPZ-REEL7	ADA4432-1 / ADA4432-1BCPZ-R7	ADA4432-1 / ADA4432-1WBCPZ-R7
ADA4433-1 / ADA4433-1BCPZ-R7	ADA4433-1 / ADA4433-1WBCPZ-R7			

Appendix B - Revision History

Rev	Publish Date	Effectivity Date	Rev Description
Rev. -	25-Nov-2013	15-Apr-2014	Initial Release

Analog Devices, Inc.

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